

PATENT



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of:

Salman Akram

Serial No.: 09/388,031

Filed: September 1, 1999

For: METALLIZATION STRUCTURES
FOR SEMICONDUCTOR DEVICE
INTERCONNECTS, METHODS FOR
MAKING SAME, AND
SEMICONDUCTOR DEVICES
INCLUDING SAME

Examiner: E. Lee

Group Art Unit: 2815

Attorney Docket No.: 3442US (96-428)

11/B
7-18-01
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AMENDMENT

Box Non Fee Amendment
Commissioner for Patents
Washington, D.C. 20231

Sir:

The following amendments and remarks are filed in response to the Examiner's remarks in the Office Action mailed March 29, 2001, the three-month shortened statutory period for response to which expires on June 29, 2001.